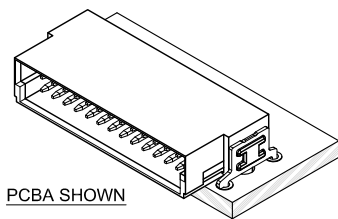


< ORDERING INFORMATION >

SMC03RD XX XXX 3

SERIES NO. _____
 1.27 SMC Male Connector
 Dual Row R/A SMT Type
 (Board Lock Through-Hole)
 CONTACT POSITION
 See DIM-TABLE

PACKAGE
 3: Tape & Reel
 CONTACT PLATING
 600: Selective Gold Flash Plated
 (1μ" Min.)
 605: 5μ" selective Gold Plated
 630: 30μ" selective Gold Plated



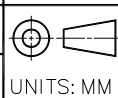
Specification

Insulator Material: High Temp. Thermoplastic, UL94V-0.
 Contact Material: Phosphor Bronze.
 Board Lock Material: Brass.
 Contact Plating: Au on Contact Area.
 Sn (100μ" Min.) on Solder tail.
 Nickel (Contact - 80μ" Min. / Solder tail - 50μ" Min.)
 Sn(100μ" Min.) over Nickel (40μ" Min.)
 Board Lock Plating: Sn(100μ" Min.) over Nickel (40μ" Min.)
 Current Rating: 1.7A Max.
 Contact Resistance: 25 Milliohms Max.
 Insulator Resistance: 1000 Megohms Min.
 Dielectric Withstanding: 500V AC for 1 Minute.
 Operating Temperature: -55°C ~ +125°C.
 Max. Processing Temp.: 230°C for 30~60 seconds.
 260°C for 10 seconds.

DIM-TABLE

PIN NO.	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	DIM G
10	11.43	7.30	5.08	8.30	9.50	10.60	9.10
12	12.70	8.57	6.35	9.57	10.77	11.87	10.37
16	15.24	11.11	8.89	12.11	13.31	14.41	12.91
20	17.78	13.65	11.43	14.65	15.85	16.95	15.45
24	20.32	16.19	13.97	17.19	18.39	19.49	17.99
26	21.59	17.46	15.24	18.46	19.66	20.76	19.26
30	24.13	20.00	17.78	21.00	22.20	23.30	21.80
32	25.40	21.27	19.05	22.27	23.47	24.57	23.07
40	30.48	26.35	24.13	27.35	28.55	29.65	28.15
50	36.83	32.70	30.48	33.70	34.90	36.00	34.50
68	48.26	44.13	41.91	45.13	46.33	47.43	45.93
80	55.88	51.75	49.53	52.75	53.95	55.05	53.55

6		New Version	2021,05,11
	REV.	DESCRIPTION	DATE
	DR. Shun	CHK. Ren	APP. Peter



TOLERANCE (UNLESS SPECIFIED)
 X.X = ±0.25
 X.XX = ±0.15
 X.XXX = ±0.05
 ANG. = ± 2°



TITLE: 1.27 SMC Male Connector
 Dual Row Right Angle SMT Type
 (Board Lock Through-Hole)

DWG NO. SMC03RD-C

SHEET 1/1
 REV. A